



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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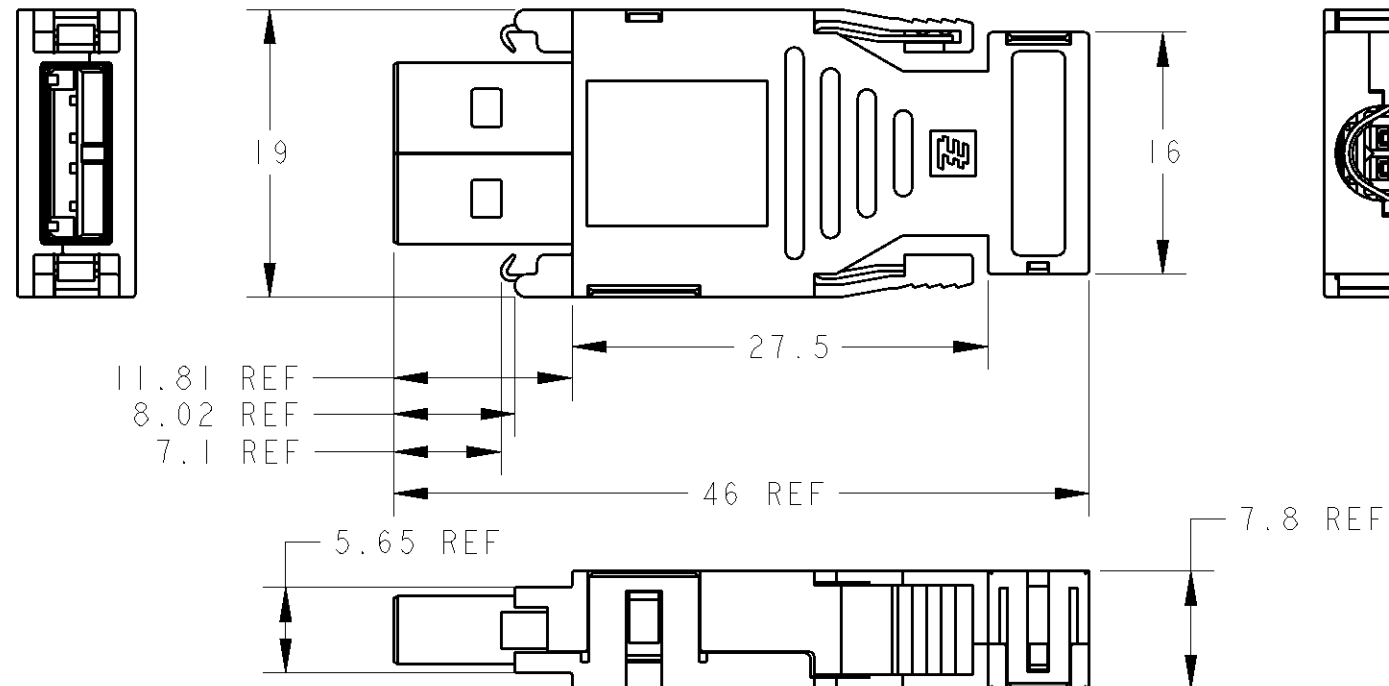
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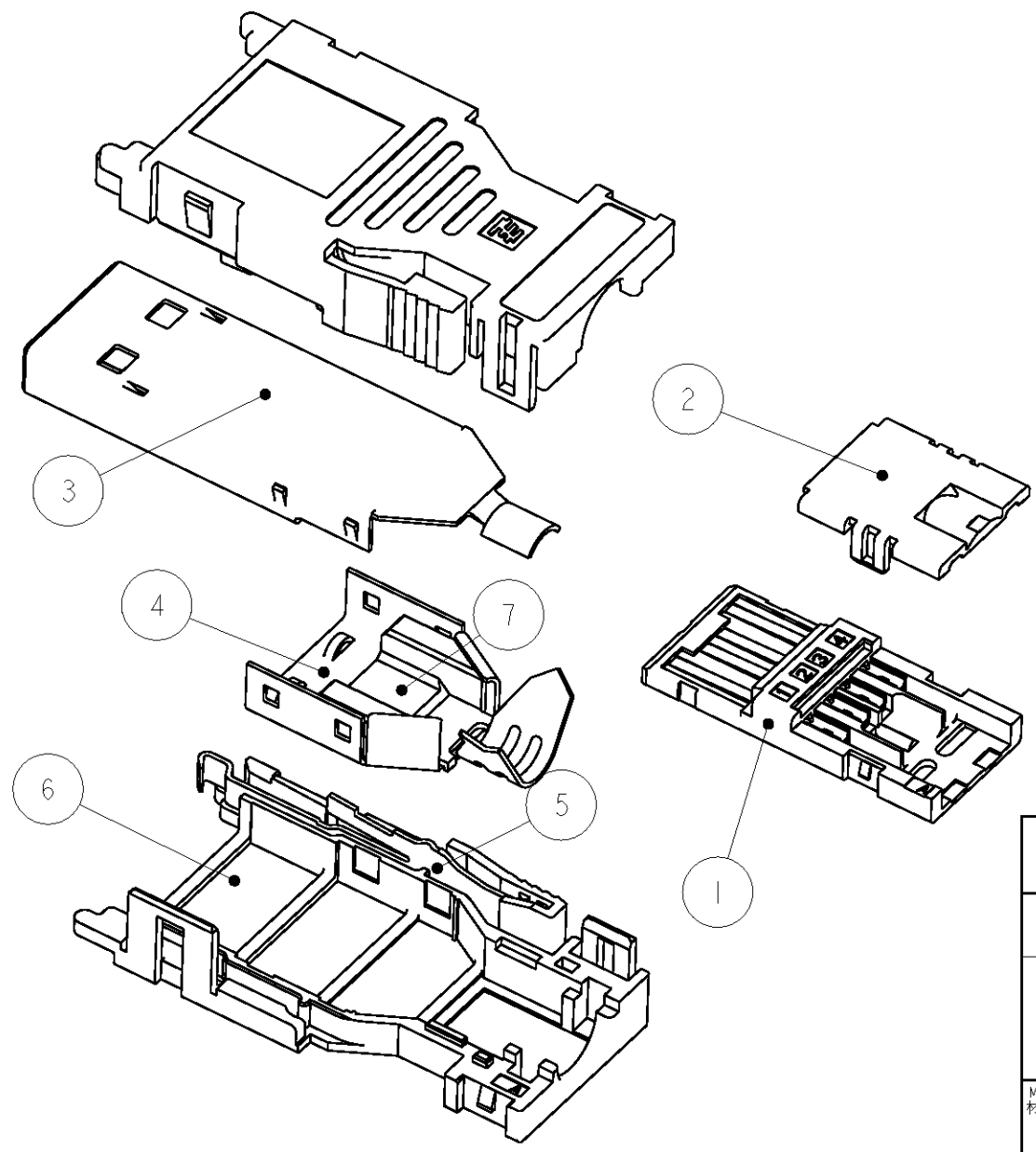
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LOC	DIST	REVISIONS					
J	-	P	LTR	DESCRIPTION	DATE	DWN	APVD
		C1		REVISED PER ECO-11-005030	26APR11	RK	HMR



-1:本図
-1:AS SHOWN



ITEM NO.	MATERIAL / FINISH	PART NAME	ITEM NO.
1	POLYAMIDE OF GLASS FILLED PLASTIC(UL94V-0) ガラス入りポリアミド系樹脂 UL94V-0	RETENTION HSG リテンション ハウジング	7
2	OLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入り熱可塑性ポリエステル系樹脂 UL94V-0	COVER HSG カバー ハウジング	6
2	STAINLESS STEEL ステンレス鋼	LOCK SPRING ロック スプリング	5
1	STEEL/UNDER:COPPER PLATING, TOP: Ni PLATING 鋼/下地:銅めっき, 表面:ニッケルめっき	BACK SHELL OF PLUG バック シェル	4
1	STEEL/UNDER:COPPER PLATING, TOP: Ni PLATING 鋼/下地:銅めっき, 表面:ニッケルめっき	FRONT SHELL OF PLUG フロント シェル	3
1	POLYESTER OF GLASS FILLED THERMO PLASTIC(UL94V-0) ガラス入り熱可塑性ポリエステル系樹脂 UL94V-0	CAP HSG キャップ ハウジング	2
1	CONTACT(COPPER ALLOY/ UNDER ALL SURFACE: Ni PLATING 1.27 μ m MIN TOP CONTACT AREA: Au PLATING 0.76 μ m MIN SOLDERING AREA: Tin PLATING 2 μ m MIN) HSG(POLYAMIDE OF GLASS FILLED PLASTIC(UL94V-0)) コンタクト(銅合金/ 全面:ニッケルめっき下地 1.27 μ m以上 表面 接点部:金めっき 0.76 μ m以上 半田付け部:錫めっき 2 μ m以上) ハウジング(ガラス入りポリアミド系樹脂 UL94V-0)	PLUG HSG ASSY プラグ ハウジング アセンブリ	1
REQUIRED PAR ASSEMBLY	MATERIAL / FINISH 材料/仕上げ	PART NAME 部品名称	ITEM NO.

DIMENSIONS: 単位: 概 mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 一般公差 ± 0.3 0 PLC \pm 1 PLC \pm 2 PLC \pm 3 PLC \pm 4 PLC \pm ANGLES \pm	DWN S. INOMATA 21DEC2007	TE Connectivity	NAME 名称 INDUSTRIAL USB PLUG CONNECTOR KIT	
		MATERIAL 材料 -			FINISH 仕上 -
CUSTOMER DRAWING			SCALE 尺度 2:1	SHEET OF 1	REV C1